data of spin valve devices in test patterns.

Table 11
Spin Valve Film Constitution:

5 nanometer Ta/free layer/3 nm Cu/ferromagnetic layer A/0.9 nm Ru/ferromagnetic layer B/10 nm IrMn/5 nanometer Ta Device Constitution: lead-overlaid structure (with no shield) Subbing hard film/longitudinal bias of CoPt/FeCo is formed on the non-patterned lower shield and lower cap, and the electrode spacing is narrower than the longitudinal bias spacing. Electrode spacing = 1.3 μ m

Egrana	Гъ	T	T = : : :	T
1	1			Breakdow
i e		Layer	_	n Voltage
Layer A	Layer B			
			Voltage	
2nmCoFe	1.5nmCoF	3nmCoFe/	not	70V
	e	1.5nmNiF	reversed	
		е		
2.5nmCoF	2nmCoFe	3nmCoFe/	not	75V
е		1.5nmNiF	reversed	
		е		
3nmCoFe	2.5nmCoF	4nmCoFe/	not	70V
	е	1.8nmNiF	reversed	
		е		
2nmCoFe	1.7nmCo	0.5nmCoF	not	70V
		e/	reversed	
		4nmNiFe		
2.4nmCoF	1.7nmCoF	1nmCoFe/	65V	75V
е	е	3nmNiFe		
2.4nmCoF	2.1nmCoF	1nmCoFe/	65V	75V
е	е	3nmNiFe		, - ,
3nmCoFe	3nmCoFe	4nmCoFe/	50V	75V
		1.8nmNiF		
		е		
3nmCoFe	2nmCoFe	3nmCoFe/	55V	75V
		1.5nmNiF		
		е		
3nmCoFe	2.8nmCoF	1nmCoFe/	55V	70V
	е	3nmNiFe	-	
	2.5nmCoFe 3nmCoFe 2nmCoFe 2.4nmCoFe 2.4nmCoFe 3nmCoFe	magnetic Layer B 2nmCoFe 1.5nmCoF e 2.5nmCoF 2nmCoFe e 3nmCoFe 2.5nmCoF e 2nmCoFe 1.7nmCoF e 2.4nmCoF 2.1nmCoF e 3nmCoFe 2.1nmCoF e 3nmCoFe 3nmCoFe 3nmCoFe 2.8nmCoFe	magnetic Layer B 2nmCoFe	magnetic Layer A Layer B Layer Layer B Layer Magnetic zation Reversal Voltage 2nmCoFe 1.5nmCoF e 2.5nmCoF e 3nmCoFe/ 1.5nmNiF e 3nmCoFe/ 1.5nmNiF e 3nmCoFe/ 1.8nmNiF e 2.4nmCoF e 1.7nmCoF e 2.4nmCoF e 3nmCoFe/ 2.1nmCoF e 3nmNiFe 2.4nmCoF e 3nmCoFe 2.1nmCoF e 3nmNiFe 3nmCoFe/ 2.1nmCoF e 3nmNiFe 3nmNiFe 3nmCoFe 3nmCoFe/ 1.8nmNiF e 3nmCoFe/ 1.5nmNiF e 3nmCoFe/ 1.5nmNiF e 3nmCoFe/ 1.5nmNiF e

In ESD, a magnetic field essentially of the current magnetic field is applied to the pinned magnetic layer in such manner that the magnetic field intensity to the ferromagnetic layer B is larger than that to the ferromagnetic layer A, while, on the other hand, the current magnetic field ratio, $H(\text{current})_B/H(\text{current})_A$ is nearly equal to the inverse ratio of magnetic thicknesses, $(Ms \cdot t)_A/(Ms \cdot t)_B$. In that condition, therefore, the magnetic energy changes due to the ESD current field of the ferromagnetic layers A and B cancel, thereby resulting in that the total energy change of:

 $\{(Ms \cdot t) \cdot H(current)\}_{A} - \{(Ms \cdot t) \cdot H(current)\}_{B}$

is reduced. As a result, the magnetization of the pinned magnetic layer could not be moved in the ESD current magnetic field.

As in Fig. 23C, when the ferromagnetic layer A is 3 nanometers thick and the ferromagnetic layer B is 2 nanometers thick and therefore $(Ms \cdot t)_B/(Ms \cdot t)_A = 0.67$, then H_{UA}^* is lower than that in the case of Fig. 23A where both the ferromagnetic layers A and B are 3 nanometers thick, and therefore, the thermal stability of the pinned magnetic layer in the case of Fig. 23C is lower than that in the case of Fig. 23A. In that case where the magnetic thickness of the ferromagnetic layer B is smaller than that of the ferromagnetic layer A, it is desirable that the current flow direction of the sense current